

Electronic Patent Application Fee Transmittal**Application Number:** 10527604**Filing Date:** 15-Mar-2005**Title of Invention:** Thermoplastic resin composition and moldings thereof**First Named Inventor/Applicant Name:** Kazuhiko Maeda**Filer:** Joshua Ryan/Vivian Pena**Attorney Docket Number:** SPL-05-1048

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees**Description****Fee Code****Quantity****Amount****Sub-Total in
USD(\$)****Basic Filing:****Pages:****Claims:****Miscellaneous-Filing:****Petition:****Patent-Appeals-and-Interference:****Post-Allowance-and-Post-Issuance:****Extension-of-Time:**

Extension - 3 months with \$0 paid

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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1110